

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of	:	Customer Number: 89518
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Mou-Shiung Lin et al.	:	Confirmation Number: 6103
	:	
Application No.: 10/055,560	:	Group Art Unit: 2813
	:	
Filed: January 22, 2002	:	Examiner: Mitchell, James M.
	:	

**For: INTEGRATED CHIP PACKAGE STRUCTURE USING METAL SUBSTRATE AND  
METHOD OF MANUFACTURING THE SAME**

**RESPONSE TO NOTIFICATION OF NON-COMPLIANT AMENDMENT**

Mail Stop AMENDMENT  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**CERTIFICATE OF ELECTRONIC TRANSMISSION**

I hereby certify that this correspondence is being electronically-transmitted to the  
United States Patent and Trademark Office on September 24, 2009.  
/Tobi Terry/

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Tobi Terry

Sir:

This Response is being submitted responsive to the Office Communication dated August  
24, 2009.

**Amendments to Claims** begin on page 2 of this paper.

**Remarks** begin on page 9 of this paper.